

EQUIPMENT DIVISION

Inseto's Equipment Division provides fabrication, assembly, test & inspection equipment for the research and production of Semiconductor, Microelectronic and related advanced electronic devices etc., as well as products for high technology & industrial manufacturing.

We are a leading supplier of lithography equipment for mask alignment, resist coating and development, plus semiconductor furnaces, wafer bonders, probing systems, dicing saws and diamond scribing machines, die bonders and sorters, inspection equipment, ultrasonic wire bonding machines, plasma cleaners and etching systems, vacuum solder reflow ovens, material testers for wire pull and shear testing etc.



BENCHTOP PLASMA CLEANERS BY PLASMA ETCH

- Compact low-cost plasma cleaning, etching and ashing equipment
- Robust, reliable and affordable
- For use in research and development labs, testing & sterilisation facilities, Universities and other production environments
- PLC or PC controlled
- Models for processing small to large samples



MASK ALIGNERS BY SÜSS MICROTEC

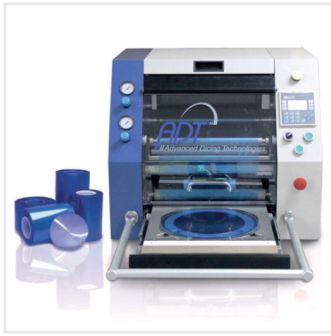
- High-quality mask and bond aligners
- Used by research, development and production facilities worldwide
- Reliable, precision alignment and high resolution printing capabilities
- Small footprint, ease of use, quality results and long term reliability
- Patented exposure optics with LED or mercury lamp houses



WAFER PROBING SYSTEMS BY SEMIPROBE

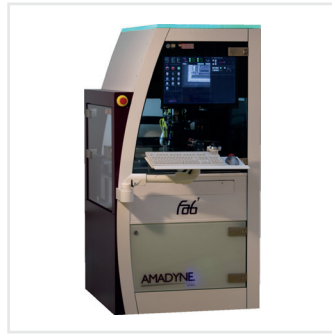
- Affordable manual semi and automatic equipment
- Test individual die, partial or full wafers from 50mm to 450mm
- DC or HF base configurations
- Robust small footprints and modular designs
- Extensive options: thermal chucks, dark box, manipulators etc

INSETO EQUIPMENT DIVISION



DICING EQUIPMENT & CONSUMABLES

- Manual & semi-automatic wafer mounters
- Manual, semi & fully automatic dicing saws
- Precision diamond scribes
- Peripheral equipment for washing, UV curing, filtration, cooling etc.
- Dicing blades & accessories



FLEXIBLE MICROELECTRONICS ASSEMBLY & AUTOMATIC DIE BONDING SYSTEMS BY AMADYNE

- Stand-alone or inline systems
- Processes include: dispensing, epoxy and eutectic bonding, die sorting, flip chip, bar stacking, inspection and test integration etc.



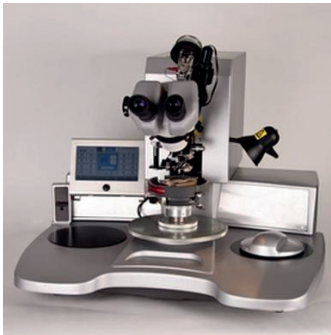
THERMAL PROCESSING EQUIPMENT BY ATV TECHNOLOGIE

- Multi-purpose semiconductor quartz tube furnaces for research or production
- Table-top to inline vacuum solder reflow & brazing systems
- Sintering press for LTCC and other applications
- High precision hot plates & chucks



KULICKE & SOFFA WIRE BONDRERS

- Automatic wedge bonders for microelectronic and battery bonding with wire or ribbon
- Manual load & inline automatic ball bonders for microelectronic and semiconductor devices
- High speed automatic Wafer Bumpers for up to 300mm wafers
- Wire Bonding Capillaries



MANUAL WIRE BONDRERS - MPP

- Formerly K&S Manual Bonder Division
- Gold Ball & Bump Bonding Models
- Wedge & Ribbon Bonding Models
- Convertible Ball & Wedge Bonding Models
- All with touch screen and digital controls



BOND TESTING SYSTEMS BY NORDSON DAGE

- Multi-function bond testers for wire pull, die & bond shear, tweezer & stud pull, bump pull & shear etc.
- Micro materials & advanced bond testing, including automation, flex-bend, push-pull, crush, fatigue, creep etc.
- Wafer Level Bond Tester for manual to fully automated testing



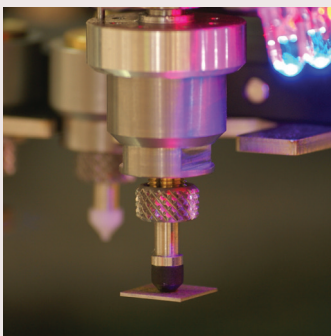
MANUAL DIE ATTACH AND DIE SORT EQUIPMENT BY TRESKY AG

- Low cost, flexible, manual die bond, sort and assembly systems
- Ergonomic controls with versatile modular designs
- High accuracy flip chip alignment capabilities
- Low-high force bonding option



INSETO TECHNICAL SUPPORT SERVICES, EXPERIENCED TEAM PROVIDING:

- Process reviews & improvements
- Machine repairs & breakdowns
- Certified maintenance & calibrations
- Annual support contracts
- Equipment & process training classes



Established in 1987, and ISO-Certified since 2005, Inseto supplies equipment, materials and consumables to microelectronic manufacturers and research institutes in the UK, Ireland and Nordic Regions.

Customer support activities are at the centre of Inseto's "Total Customer Service" philosophy, where we aim to understand, communicate and fulfil the needs of our customers, better than any competitor. We are committed to meeting these requirements through the application of high standards of quality and customer care, both before and after sales, by continually investing in training & adopting a policy of continuous improvement in our Company and its people.